(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
16 February 2012 (16.02.2012)

PCT

(10) International Publication Number
WO 2012/021349 A2

(51) International Patent Classification:
H01L 21/60 (2006.01)

(21) International Application Number:
PCT/US2011/046420

(22) International Filing Date:
3 August 2011 (03.08.2011)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
61/372,430 10 August 2010 (10.08.2010) US

(71) Applicant *(for all designated States except US)*: **KULICKE AND SOFFA INDUSTRIES, INC.** [US/US]; 1005 Virginia Drive, Fort Washington, PA 19034 (US).

(72) Inventor; and

(75) Inventor/Applicant *(for US only)*: **GILLOTTI, Gary, S.** [US/US]; 104 Stafford Circle, Lansdale, PA 19446 (US).

(74) Agent: **SPLETZER, Christopher, M.**; Kulicke And Soffa Industries, INC., 1005 Virginia Drive, Fort Washington, PA 19034 (US).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, QA, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— *of inventorship (Rule 4.17(iv))*

Published:

— *without international search report and to be republished upon receipt of that report (Rule 48.2(g))*

(54) Title: WIRE LOOPS, METHODS OF FORMING WIRE LOOPS, AND RELATED PROCESS

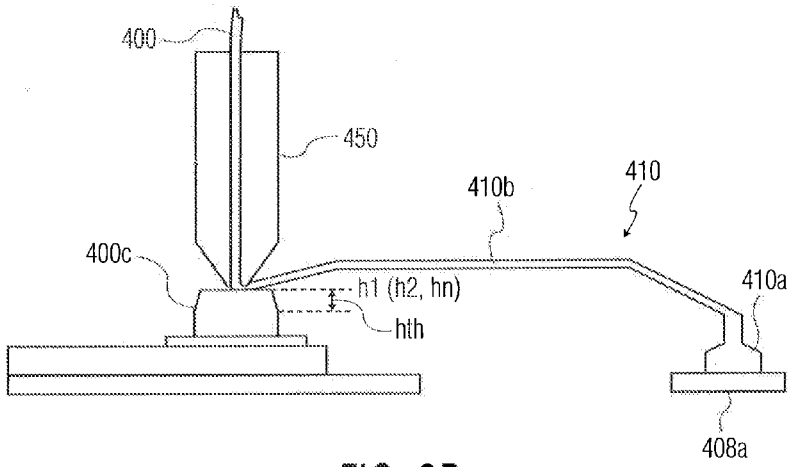


FIG. 3B

(57) Abstract: A method of forming a wire loop is provided. The method includes the steps of: (1) forming a conductive bump on a bonding location using a wire bonding tool; (2) bonding a portion of wire to another bonding location using the wire bonding tool; (3) extending a length of wire from the bonded portion of wire toward the bonding location; (4) lowering the bonding tool toward the bonding location while detecting a height of a tip of the wire bonding tool; and (5) interrupting the lowering of the wire bonding tool during step (4) if the wire bonding tool reaches a predetermined height.

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